# DISCRETE SEMICONDUCTORS

# DATA SHEET

# **BFS520**NPN 9 GHz wideband transistor

Product specification
File under Discrete Semiconductors, SC14

September 1995





**BFS520** 

#### **FEATURES**

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability
- SOT323 envelope.

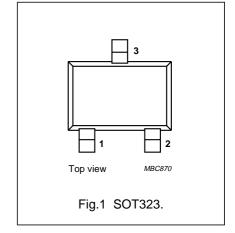
# **DESCRIPTION**

NPN transistor in a plastic SOT323 envelope.

It is intended for wideband applications such as satellite TV tuners, cellular phones, cordless phones, pagers etc., with signal frequencies up to 2 GHz.

# **PINNING**

PIN DESCRIPTION						
Code: N2						
1	base					
2	emitter					
3 collector						



#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	_	20	V
V <sub>CES</sub>	collector-emitter voltage	R <sub>BE</sub> = 0	_	_	15	V
I <sub>C</sub>	DC collector current		_	_	70	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 118$ °C; note 1	_	_	300	mW
h <sub>FE</sub>	DC current gain	$I_C = 20 \text{ mA}; V_{CE} = 6 \text{ V}; T_j = 25 ^{\circ}\text{C}$	60	120	250	
f <sub>T</sub>	transition frequency	$I_C = 20 \text{ mA}; V_{CE} = 6 \text{ V}; f = 1 \text{ GHz};$ $T_{amb} = 25 \text{ °C}$	_	9	_	GHz
G <sub>UM</sub>	maximum unilateral power gain	$I_c = 20 \text{ mA}; V_{CE} = 6 \text{ V}; f = 900 \text{ MHz};$ $T_{amb} = 25 \text{ °C}$	_	15	_	dB
F	noise figure	$I_c = 5 \text{ mA}; V_{CE} = 6 \text{ V}; f = 900 \text{ MHz};$ $T_{amb} = 25 \text{ °C}$	_	1.1	1.6	dB

### **LIMITING VALUES**

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER CONDITIONS		MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	20	V
V <sub>CES</sub>	collector-emitter voltage	R <sub>BE</sub> = 0	_	15	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	2.5	٧
I <sub>C</sub>	DC collector current		_	70	mA
P <sub>tot</sub>	total power dissipation	up to T <sub>s</sub> = 118 °C; note 1	_	300	mW
T <sub>stg</sub>	storage temperature		-65	150	°C
Tj	junction temperature		_	175	°C

#### Note

1.  $T_s$  is the temperature at the soldering point of the collector tab.

Philips Semiconductors Product specification

# NPN 9 GHz wideband transistor

**BFS520** 

#### THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	up to $T_s = 118$ °C; note 1	190 K/W

#### Note

1.  $T_s$  is the temperature at the soldering point of the collector tab.

#### **CHARACTERISTICS**

 $T_i = 25$  °C, unless otherwise specified.

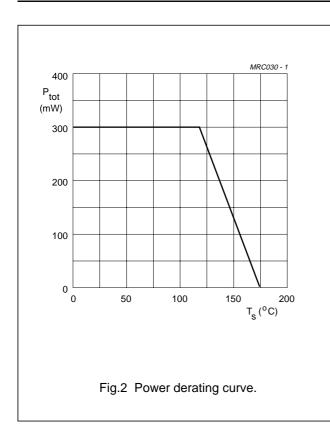
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	collector cut-off current $I_E = 0$ ; $V_{CE} = 6 \text{ V}$		_	50	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 20mA; V <sub>CE</sub> = 6 V	60	120	250	
Ce	emitter capacitance	$I_C = i_c = 0$ ; $V_{EB} = 0.5 \text{ V}$ ; $f = 1 \text{ MHz}$	_	1	_	pF
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = 6 \text{ V}$ ; $f = 1 \text{ MHz}$	_	0.5	_	pF
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CB</sub> = 6 V; f = 1 MHz	_	0.4	_	pF
f <sub>T</sub>	transition frequency	$I_C = 20 \text{ mA}; V_{CE} = 6 \text{ V}; f = 1 \text{ GHz};$ $T_{amb} = 25 \text{ °C}$	_	9	_	GHz
G <sub>UM</sub>	maximum unilateral power gain (note 1)	$I_C = 20 \text{ mA}; V_{CE} = 6 \text{ V}; f = 900 \text{ MHz};$ $T_{amb} = 25 \text{ °C}$	-	15	_	dB
		$I_C = 20 \text{ mA}; V_{CE} = 6 \text{ V}; f = 2 \text{ GHz}; $ $T_{amb} = 25 \text{ °C}$	_	9	_	dB
S <sub>21</sub>   <sup>2</sup>	insertion power gain	$I_C = 20 \text{ mA}; V_{CE} = 6 \text{ V}; f = 900 \text{ MHz};$ $T_{amb} = 25 \text{ °C}$	13	14	_	dB
F	noise figure	$\Gamma_{\rm s} = \Gamma_{\rm opt}$ ; $I_{\rm C} = 5$ mA; $V_{\rm CE} = 6$ V; $f = 900$ MHz; $T_{\rm amb} = 25$ °C	_	1.1	1.6	dB
		$\Gamma_{\rm s}$ = $\Gamma_{\rm opt}$ ; $I_{\rm C}$ = 20 mA; $V_{\rm CE}$ = 6 V; $f$ = 900 MHz; $T_{\rm amb}$ = 25 °C	_	1.6	2.1	dB
		$\Gamma_{\text{S}} = \Gamma_{\text{opt}}$ ; $I_{\text{C}} = 5$ mA; $V_{\text{CE}} = 6$ V; $f = 2$ GHz; $T_{\text{amb}} = 25$ °C	_	1.9	_	dB
P <sub>L1</sub>	output power at 1 dB gain compression	$I_{c}$ = 20 mA; $V_{CE}$ = 6 V; $R_{L}$ = 50 $\Omega$ ; $f$ = 900 MHz; $T_{amb}$ = 25 °C	_	17	_	dBm
ITO	third order intercept point	note 2	_	26	_	dBm

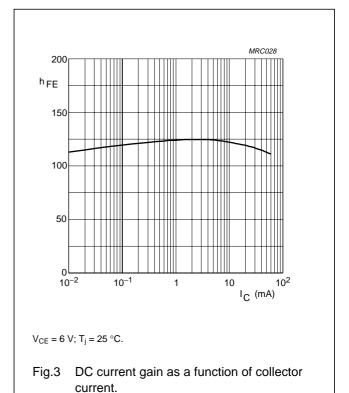
#### **Notes**

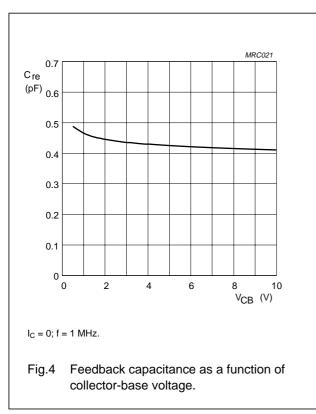
1.  $G_{UM}$  is the maximum unilateral power gain, assuming  $S_{12}$  is zero and

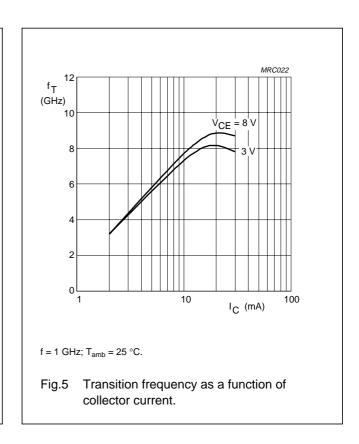
$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1-|S_{11}|^2)(1-|S_{22}|^2)} dB.$$

2.  $I_{C}$  = 20 mA;  $V_{CE}$  = 6 V;  $R_{L}$  = 50  $\Omega$ ; f = 900 MHz;  $T_{amb}$  = 25 °C;  $f_{p}$  = 900 MHz;  $f_{q}$  = 902 MHz; measured at  $f_{(2p-q)}$  = 898 MHz and at  $f_{(2q-p)}$  = 904 MHz.









**BFS520** 

In Figs 6 to 9,  $G_{UM}$  = maximum unilateral power gain; MSG = maximum stable gain;  $G_{max}$  = maximum available gain.

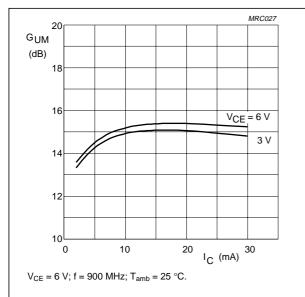
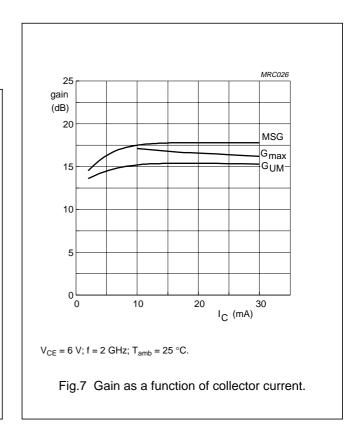
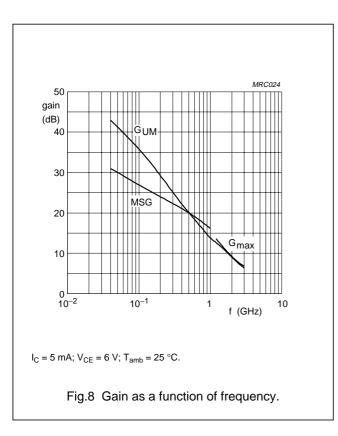
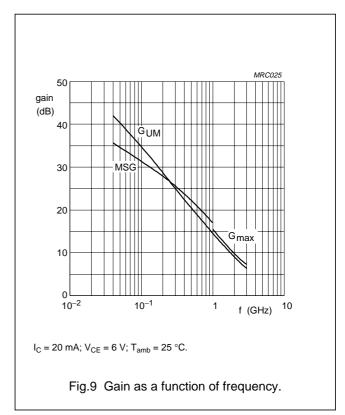


Fig.6 Maximum unilateral power gain as a function of collector current.







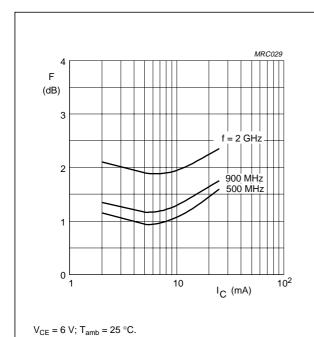


Fig.10 Minimum noise figure as a function of collector current.

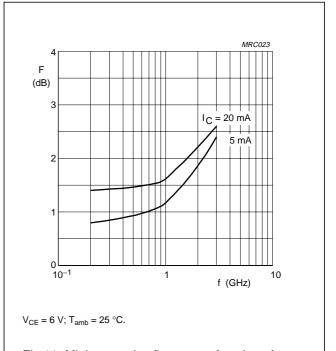
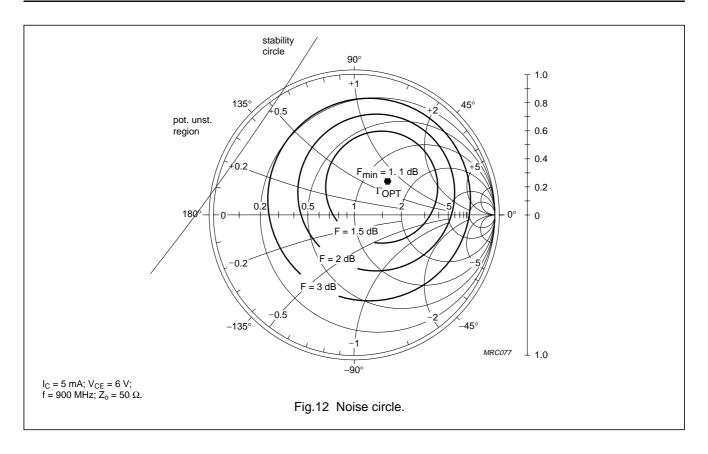
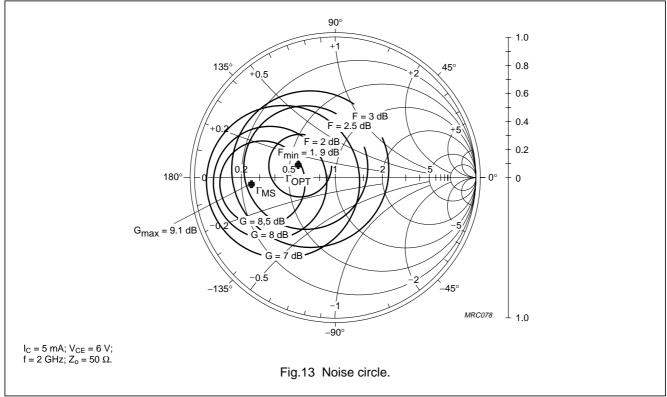


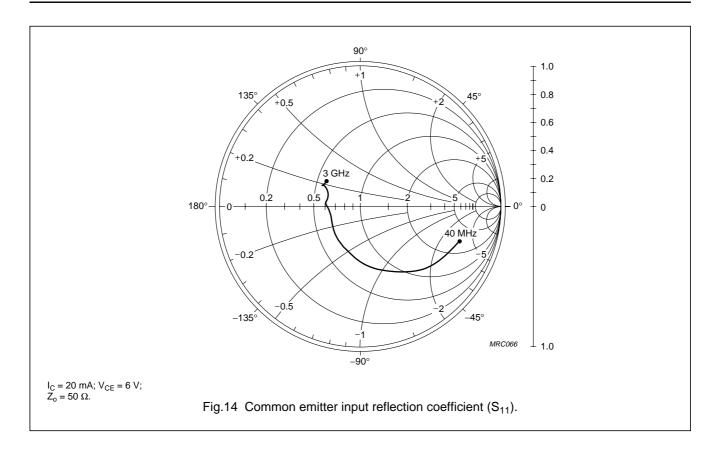
Fig.11 Minimum noise figure as a function of frequency.

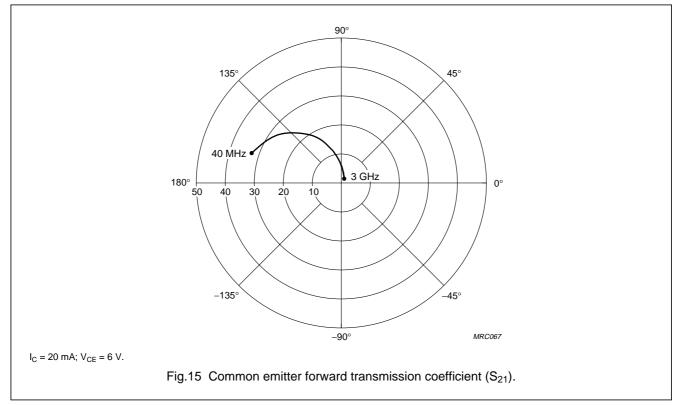


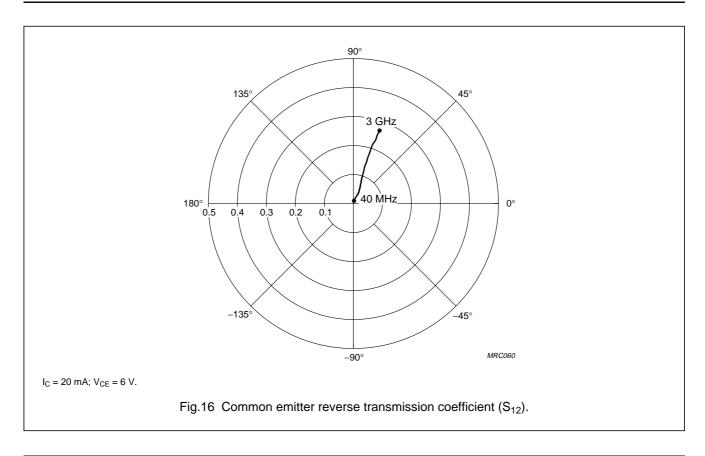


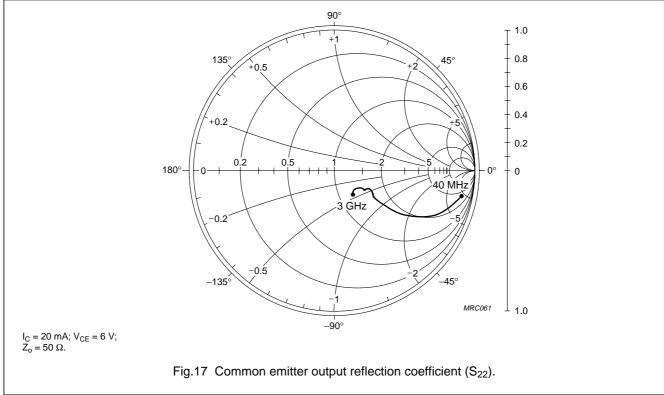
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# NPN 9 GHz wideband transistor







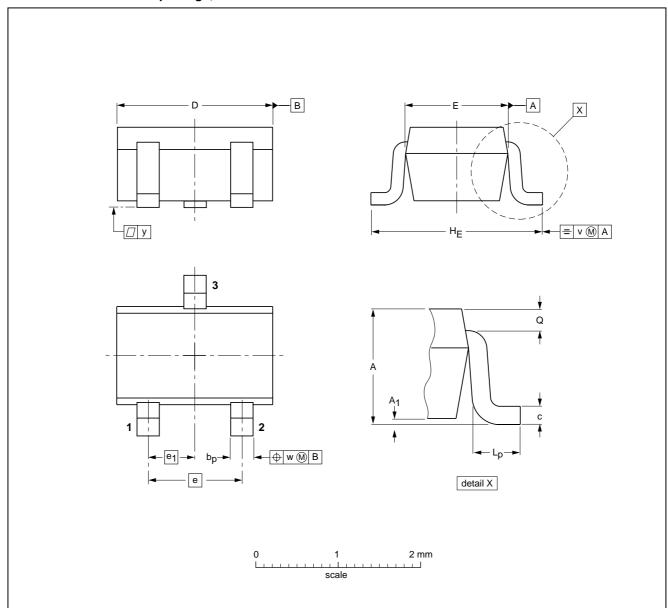


BFS520

# **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

**SOT323** 



# DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	Q	V	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE		REFER	REFERENCES			ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT323			SC-70			97-02-28

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# NPN 9 GHz wideband transistor

**BFS520** 

#### **DEFINITIONS**

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.